



Material Content Data Sheet



Halogen-Free

Sales Product Name	BTT3018EJ	Issued	26. June 2021
MA#	MA005568829		
Package	PG-TDSO-8-21	Weight*	68.07 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.119	4.58	4.58	45827	45827
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		140	
	non noble metal	zinc	7440-66-6	0.038	0.06		558	
	non noble metal	iron	7439-89-6	0.760	1.12		11162	
	non noble metal	copper	7440-50-8	30.851	45.33	46.52	453221	465081
wire	non noble metal	copper	7440-50-8	0.607	0.89	0.89	8924	8924
encapsulation	organic material	carbon black	1333-86-4	0.091	0.13		1341	
	plastics	epoxy resin	-	3.559	5.23		52288	
	inorganic material	silicondioxide	60676-86-0	26.770	39.33	44.69	393276	446905
leadfinish	non noble metal	tin	7440-31-5	0.497	0.73	0.73	7305	7305
plating	noble metal	silver	7440-22-4	0.825	1.21	1.21	12117	12117
glue	plastics	epoxy resin	-	0.165	0.24		2422	
	noble metal	silver	7440-22-4	0.777	1.14	1.38	11419	13841
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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